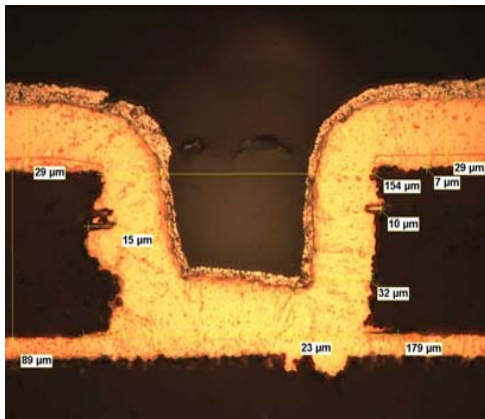


Vertical plating; microvias Single-Step.

Diameter: 150 μm
Depth: 100 μm

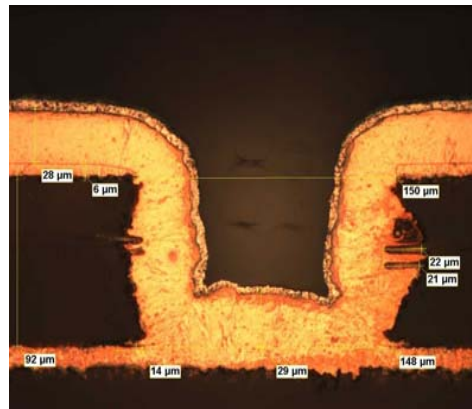


*Bottom; 28 μm Cu
Surface; 29 μm Cu*

TP = 96 %

**Rectifier:
D2R- Series
Forward CD
25 ASF**

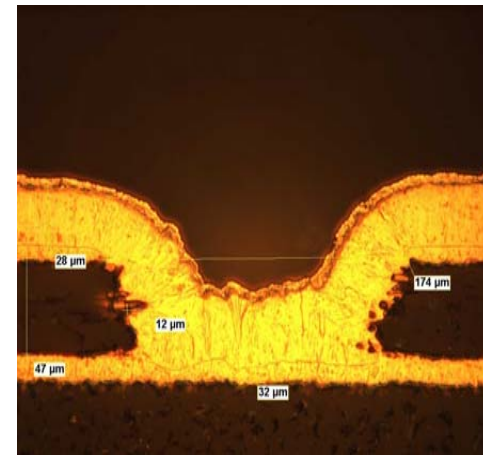
Diameter: 150 μm
Depth: 100 μm



*Bottom; 29 μm Cu
Surface; 28 μm Cu*

TP = 104 %

Diameter: 200 μm
Depth: 100 μm



*Bottom; 28 μm Cu
Surface; 32 μm Cu*

TP = 114 %